#### (19) World Intellectual Property Organization International Bureau



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## (43) International Publication Date 11 January 2001 (11.01.2001)

#### PCT

# (10) International Publication Number WO 01/02508 A1

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(51) International Patent Classification<sup>7</sup>:

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(21) International Application Number: PCT/US00/17457

(22) International Filing Date: 23 June 2000 (23.06.2000)

(25) Filing Language:

English

C09J 7/02

(26) Publication Language:

English

(30) Priority Data: 11/189081

2 July 1999 (02.07.1999) J

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229-1123 (JP).

3427 (US).

2-9-45, Higashifuchinobe,

(81) Designated States (national): KR, US.

(84) Designated States (regional): European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

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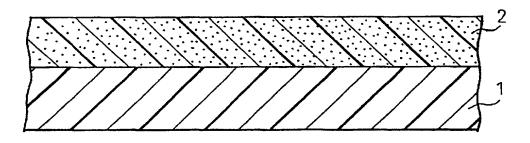
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With international search report.

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: PRESSURE SENSITIVE ADHESIVE SHEET AND PRODUCTION METHOD THEREOF



VO 01/02508 A

(57) Abstract: Problem to be solved: to provide a simple method for improving the adhesive property between a fluorine-containing material substrate and a pressure sensitive adhesive which are poor in the adhesion to each other. Means to solve the problem: when a fluorine-containing material substrate having coated thereon a pressure sensitive adhesive is irradiated with an electron beam, a chemical bond is formed between the substrate and the pressure sensitive adhesive. Furthermore, the pressure sensitive adhesive can be cured by polymerization and also the substrate can be cross-linked.